



NOMINAL SIZE = 1 in x 0.62 in  
(25,4 mm x 15,75 mm)

**Features**

- $V_{TT}$  Bus Termination Output (Output Tracks the System  $V_{REF}$ )
- 10 A Output Current
- 3.3-V, 5-V or 12-V Input Voltage
- DDR & QDR Compatible
- On/Off Inhibit (for  $V_{TT}$  Standby)
- Under-Voltage Lockout
- Operating Temp: -40 to +85 °C
- Efficiencies up to 91 %
- 57 W/in<sup>3</sup> Power Density
- Output Over-Current Protection (Non-Latching, Auto-Reset)
- Safety Agency Approvals (Pending): UL/cUL60950, EN60950, VDE
- Point-of-Load Alliance (POLA) Compatible

**Description**

The PTHxx060Y are a series of ready-to-use switching regulator modules from Texas Instruments designed specifically for bus termination in DDR and QDR memory applications. Operating from either a 3.3-V, 5-V or 12-V input, the modules generate a  $V_{TT}$  output that will source or sink up to 10 A of current to accurately track their  $V_{REF}$  input.  $V_{TT}$  is the required bus termination supply voltage, and  $V_{REF}$  is the reference voltage for the memory and chipset bus receiver comparators.  $V_{REF}$  is usually set to half the  $V_{DDQ}$  power supply voltage.

The PTHxx060Y series employs an actively switched synchronous rectifier

output to provide state-of-the-art step-down switching conversion. The products are small in size (1 in × 0.62 in), and are an ideal choice where space, performance, and high efficiency are desired, along with the convenience of a ready-to-use module.

Operating features include an on/off inhibit and output over-current protection (source mode only). The on/off inhibit feature allows the  $V_{TT}$  bus to be turned off to save power in a standby mode of operation. To ensure tight load regulation, an output remote sense is also provided.

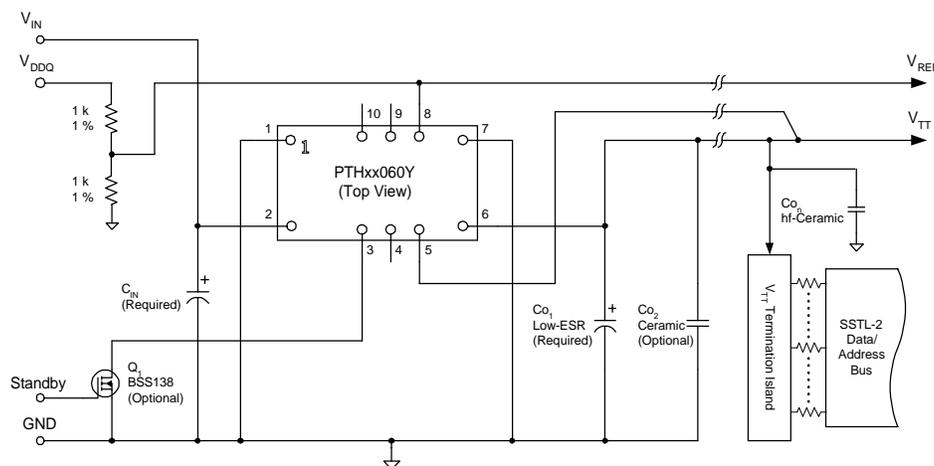
Package options include both through-hole and surface mount configurations.

**Pin Configuration**

Pin	Function
1	GND
2	$V_{in}$
3	Inhibit*
4	No Connect
5	$V_o$ Sense
6	$V_{TT}$
7	GND
8	$V_{REF}$
9	No Connect
10	No Connect

\* Denotes negative logic:  
Open = Normal operation  
Ground =  $V_{TT}$  Output Off

**Standard Application**



$C_{in}$  = Required capacitor; 330  $\mu$ F (3.3-/5-V input), 560  $\mu$ F (12-V input)  
 $C_{O1}$  = Required low-ESR electrolytic capacitor; 470  $\mu$ F (3.3-/5-V input), 940  $\mu$ F (12-V input).  
 $C_{O2}$  = Ceramic capacitance for optimum response to a 3-A ( $\pm$ 1.5-A) load transient. 200  $\mu$ F (3.3-/5-V input), 400  $\mu$ F (12-V input).  
 $C_{On}$  = Distributed hf-ceramic decoupling capacitors for  $V_{TT}$  bus; as recommended for DDR memory applications.

Ordering Information

Input Voltage (PTH□□060Yxx)		Package Options (PTHxx060Y□□) <sup>(1)</sup>		
Code	Input Voltage	Code	Description	Pkg Ref. <sup>(2)</sup>
03	3.3 V	AH	Horiz. T/H	(EUW)
05	5 V	AS	SMD, Standard <sup>(3)</sup>	(EUY)
12	12 V			

**Notes:** (1) Add “T” to end of part number for tape and reel on SMD packages only.  
 (2) Reference the applicable package reference drawing for the dimensions and PC board layout  
 (3) “Standard” option specifies 63/37, Sn/Pb pin solder material.

Pin Descriptions

**V<sub>IN</sub>:** The positive input voltage power node to the module, which is referenced to common *GND*.

**GND:** This is the common ground connection for the *V<sub>IN</sub>* and *V<sub>TT</sub>* power connections. It is also the 0-VDC reference for the control inputs.

**V<sub>REF</sub>:** The module senses the voltage at this input to regulate the output voltage, *V<sub>TT</sub>*. The voltage at *V<sub>REF</sub>* is also the reference voltage for the system bus receiver comparators. It is normally set to precisely half the bus driver supply voltage (*V<sub>DDQ</sub>* ÷ 2), using a resistor divider (see standard application). The Thevenin impedance of the network driving the *V<sub>REF</sub>* pin should not exceed 500 Ω.

**V<sub>TT</sub>:** This is the regulated power output from the module with respect to the *GND* node, and the tracking termination supply for the application data and address buses.

It is precisely regulated to the voltage applied to the module’s *V<sub>REF</sub>* input, and is active active about 20 ms after a valid input source is applied to the module. Once active it will track the voltage applied at *V<sub>REF</sub>*.

**Vo Sense:** The sense input allows the regulation circuit to compensate for voltage drop between the module and the load. For optimal voltage accuracy *Vo Sense* should be connected to *V<sub>TT</sub>*.

**Inhibit:** The Inhibit pin is an open-collector/drain negative logic input that is referenced to *GND*. Applying a low-level ground signal to this input turns off the output voltage, *V<sub>TT</sub>*. When the Inhibit is active, the input current drawn by the regulator is significantly reduced. If the Inhibit pin is left open circuit, the module will produce an output whenever a valid input source is applied.

Environmental & Absolute Maximum Ratings (Voltages are with respect to *GND*)

Characteristics	Symbols	Conditions	Min	Typ	Max	Units
Control Input Voltage	<i>V<sub>REF</sub></i>		-0.3	—	<i>V<sub>in</sub></i> + 0.3	V
Operating Temperature Range	<i>T<sub>a</sub></i>	Over <i>V<sub>in</sub></i> Range	-40 <sup>(i)</sup>	—	85	°C
Solder Reflow Temperature	<i>T<sub>reflow</sub></i>	Surface temperature of module body or pins			235 <sup>(ii)</sup>	°C
Storage Temperature	<i>T<sub>s</sub></i>	—	-40	—	125	°C
Mechanical Shock		Per Mil-STD-883D, Method 2002.3 1 msec, ½ Sine, mounted	—	500	—	G’s
Mechanical Vibration		Mil-STD-883D, Method 2007.2 20-2000 Hz	—	20	—	G’s
Weight	—		—	3.7	—	grams
Flammability	—	Meets UL 94V-O				

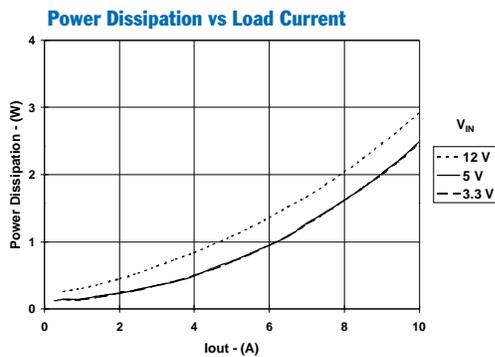
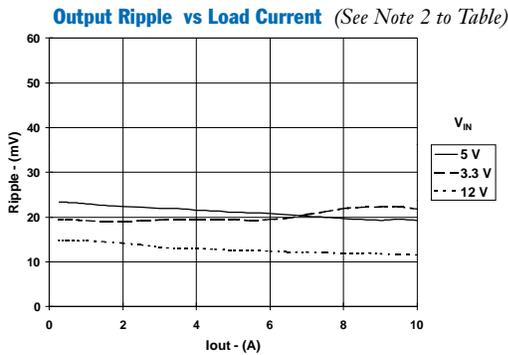
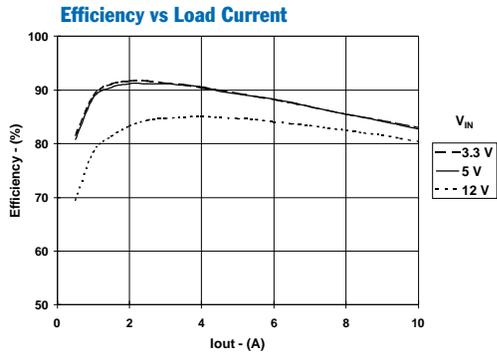
**Notes:** (i) For operation below 0 °C the external capacitors must have stable characteristics. use either a low ESR tantalum, Os-Con, or ceramic capacitor.  
 (ii) During reflow of SMD package version do not elevate peak temperature of the module, pins or internal components above the stated maximum.

**Specifications** (Unless otherwise stated,  $T_a = 25\text{ }^\circ\text{C}$ ; nominal  $V_{in}$ ;  $V_{REF} = 1.25\text{ V}$ ;  $C_{in}$ ,  $Co_1$ , &  $Co_2$  =typical values; and  $I_o = I_{o,max}$ )

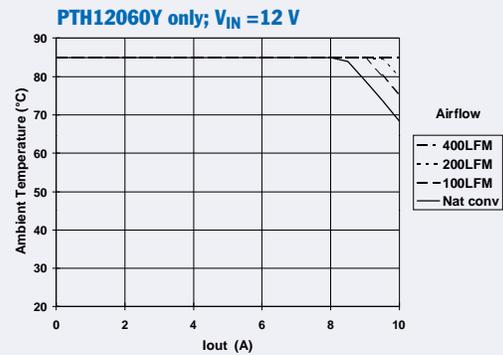
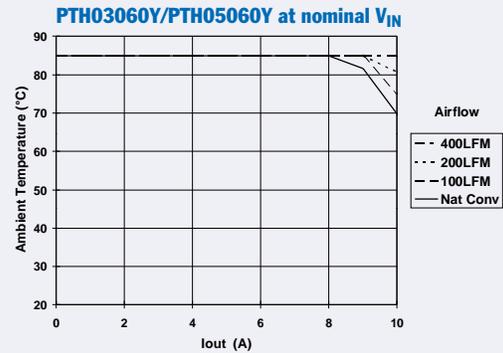
Characteristics	Symbols	Conditions	PTHxx060Y			Units		
			Min	Typ	Max			
Output Current	$I_o$	Over $\Delta V_{REF}$ range,	0	—	$\pm 10$ <sup>(1)</sup>	A		
Input Voltage Range	$V_{in}$	Over $I_o$ range	PTH03060Y	2.95	—	3.65	V	
			PTH05060Y	4.5	—	5.5		
			PTH12060Y	10.8	—	13.2		
Tracking Range for $V_{REF}$	$\Delta V_{REF}$		0.55	—	1.8	V		
Tracking Tolerance to $V_{REF}$	$ V_{TT} - V_{REF} $	Over line, load and temperature	-10	—	+10	mV		
Efficiency	$\eta$	$I_o = 8\text{ A}$	PTH03060Y	—	86	—	%	
			PTH05060Y	—	86	—		
			PTH12060Y	—	83	—		
$V_o$ Ripple (pk-pk)	$V_r$	20 MHz bandwidth	—	20	—	mVpp		
Over-Current Threshold	$I_o$ trip	Reset, followed by auto-recovery	—	20	—	A		
Load Transient Response	$t_{tr}$ $\Delta V_r$	15 A/ $\mu\text{s}$ load step, from -1.5 A to +1.5 A (See note 4)	Recovery Time	—	30	—	$\mu\text{Sec}$ mV	
			$V_o$ over/undershoot	—	25	40		
Under-Voltage Lockout	UVLO	$V_{in}$ increasing	PTH03060Y	—	2.45	2.8	V	
			PTH05060Y	—	4.3	4.45		
			PTH12060Y	—	9.5	10.4		
		$V_{in}$ decreasing	PTH03060Y	2.2	2.40	—	V	
			PTH05060Y	3.4	3.7	—		
			PTH12060Y	8.8	9	—		
Inhibit Control (pin3) Input High Voltage Input Low Voltage	$V_{IH}$ $V_{IL}$	Referenced to GND	$V_{in} - 0.5$	—	Open <sup>(2)</sup>	V		
			-0.2	—	0.6			
Input Low Current	$I_{in}$ inhibit	Pin to GND	—	-130	—	$\mu\text{A}$		
Input Standby Current	$I_{in}$ inh	Inhibit (pin 3) to GND	—	10	—	mA		
Switching Frequency	$f_s$	Over $V_{in}$ & $I_o$ ranges	PTH03060Y/PTH05060Y	550	600	650	kHz	
			PTH12060Y	200	250	300		
External Input Capacitance	$C_{in}$		PTH03060Y/PTH05060Y	330 <sup>(3)</sup>	—	—	$\mu\text{F}$	
			PTH12060Y	560	—	—		
External Output Capacitance	$Co_1, Co_2$	Capacitance value:	non-ceramic	PTH03060Y/PTH05060Y	0	470 <sup>(4)</sup>	5,500 <sup>(5)</sup>	$\mu\text{F}$
				PTH12060Y	—	940 <sup>(4)</sup>	5,500 <sup>(5)</sup>	
			ceramic	PTH03060Y/PTH05060Y	0	200 <sup>(4)</sup>	300	$\mu\text{F}$
				PTH12060Y	0	400 <sup>(4)</sup>	600	
			Equiv. series resistance (non-ceramic)		4 <sup>(6)</sup>	—	—	m $\Omega$
Reliability	MTBF	Per Bellcore TR-332 50 % stress, $T_a = 40\text{ }^\circ\text{C}$ , ground benign	6	—	—	$10^6$ Hrs		

- Notes:**
- (1) Rating is conditional on the module being soldered to a 4-layer PCB with 1 oz. copper. See the SOA curves or contact the factory for appropriate derating.
  - (2) This control pin has an internal pull-up to the input voltage  $V_{in}$ . If it is left open-circuit the module will operate when input power is applied. A small low-leakage (<100 nA) MOSFET is recommended for control. For further information, consult the related application note.
  - (3) An input capacitor is required for proper operation. The capacitor must be rated for a minimum of 500 mA rms (1,000 mA for 12-V input) of ripple current. For further information, consult the related application note on capacitor selection.
  - (4) The typical value of external output capacitance value ensures that  $V_{TT}$  meets the specified transient performance requirements for the memory bus terminations. Lower values of capacitance may be possible when the measured peak change in output current is consistently less than 3 A.
  - (5) This is the calculated maximum. The minimum ESR limitation will often result in a lower value. Consult the application notes for further guidance.
  - (6) This is the typical ESR for all the electrolytic (non-ceramic) output capacitance. Use 7 m $\Omega$  as the minimum when using max-ESR values to calculate.

**Characteristic Data;  $V_{REF} = 1.25\text{ V}$**  (See Note A)

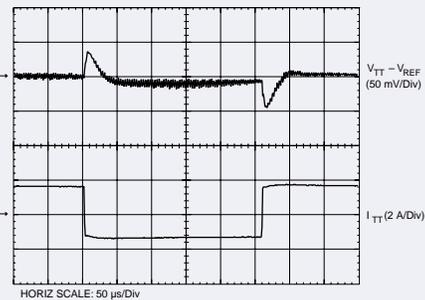


**Safe Operating Area;  $V_{REF} = 1.25\text{ V}$**  (See Note B)

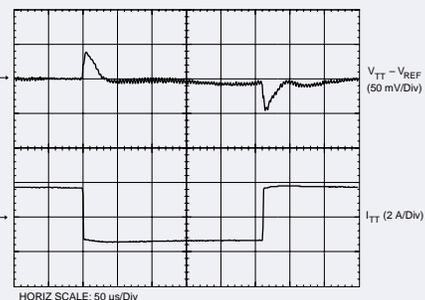


**Transient Performance for  $\Delta 3\text{-A}$  Load Change**

**PTH03060Y: Source-Sink-Source Transient**



**PTH12060Y: Source-Sink-Source Transient**

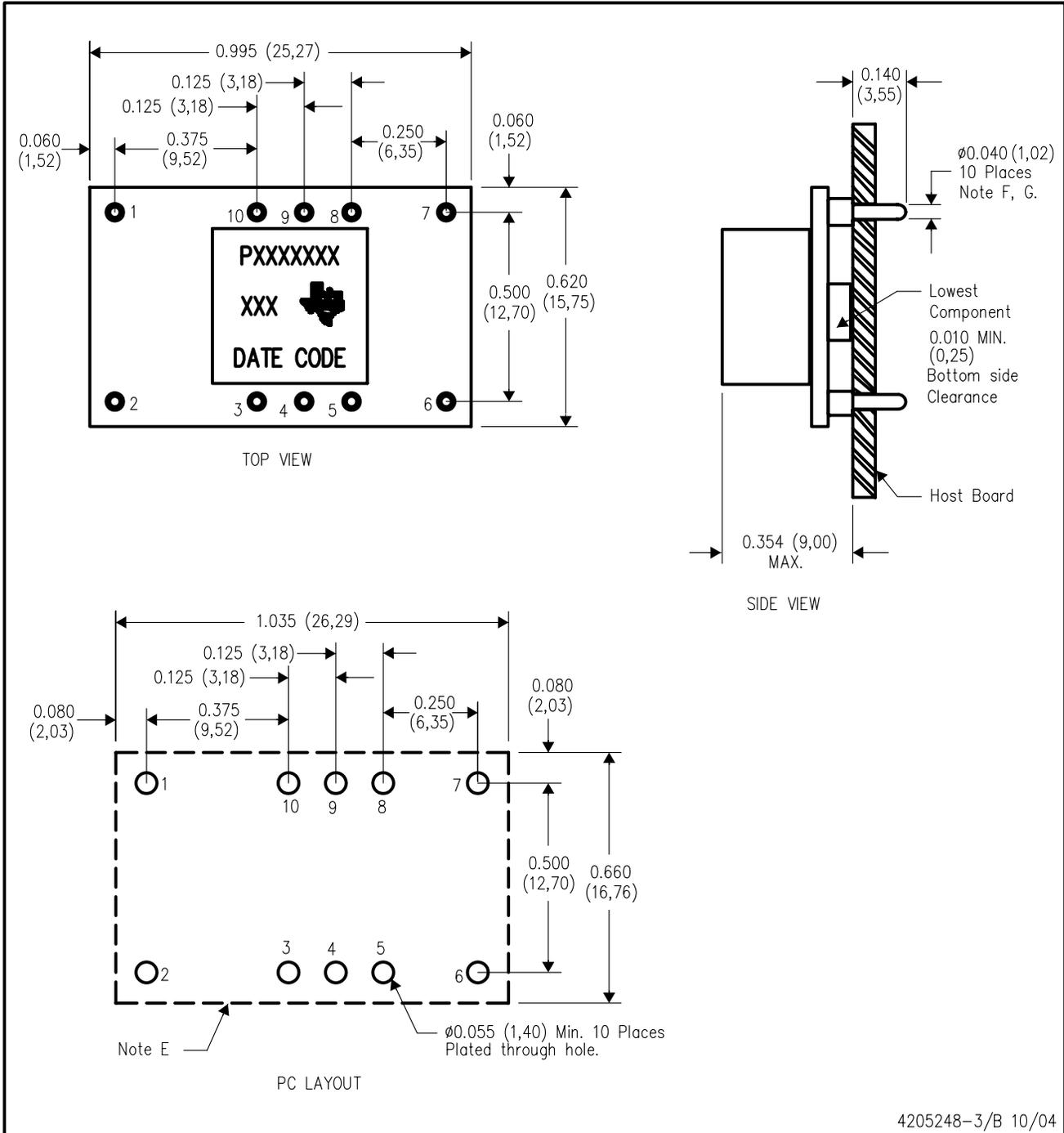


**Note A:** Characteristic data has been developed from actual products tested at 25°C. This data is considered typical data for the Converter.

**Note B:** SOA graphs represent the conditions at which internal components are at or below the manufacturer's maximum operating temperatures. Derating limits apply to modules soldered directly to a 4 in  $\times$  4 in. double-sided PCB with 1 oz. copper.

**EUW (R-PDSS-T10)**

**DOUBLE SIDED MODULE**

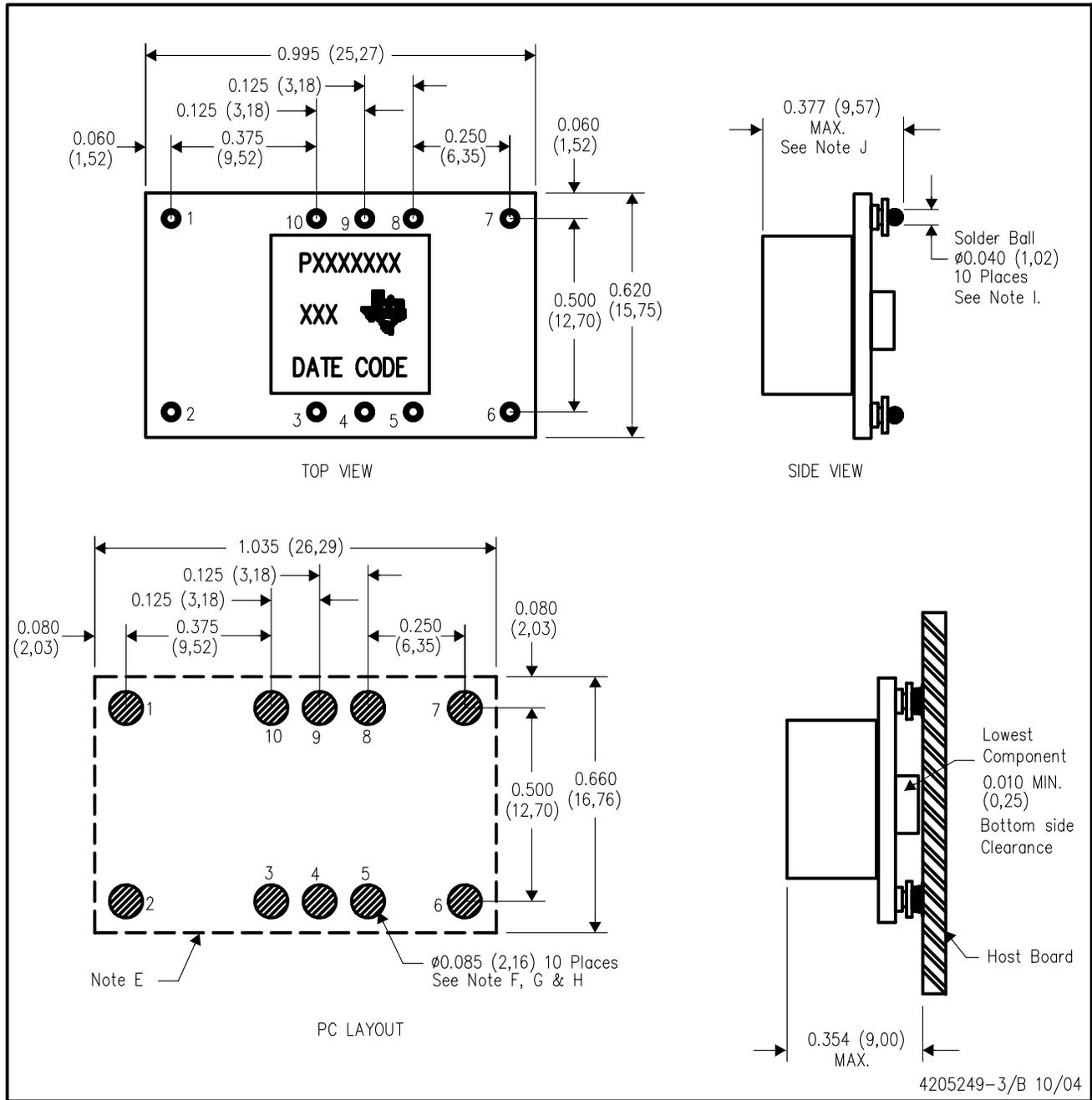


- NOTES:
- A. All linear dimensions are in inches (mm).
  - B. This drawing is subject to change without notice.
  - C. 2 place decimals are  $\pm 0.030$  ( $\pm 0,76$ mm).
  - D. 3 place decimals are  $\pm 0.010$  ( $\pm 0,25$ mm).
  - E. Recommended keep out area for user components

- F. Pins are 0.040" (1,02) diameter with 0.070" (1,78) diameter standoff shoulder.
- G. All pins: Material – Copper Alloy  
Finish – Tin (100%) over Nickel plate

**EUY (R-PDSS-B10)**

**DOUBLE SIDED MODULE**



- NOTES:
- A. All linear dimensions are in inches (mm).
  - B. This drawing is subject to change without notice.
  - C. 2 place decimals are  $\pm 0.030$  ( $\pm 0,76$ mm).
  - D. 3 place decimals are  $\pm 0.010$  ( $\pm 0,25$ mm).
  - E. Recommended keep out area for user components.
  - F. Power pin connection should utilize two or more vias to the interior power plane of 0.025 (0,63) I.D. per input, ground and output pin (or the electrical equivalent).

- G. Paste screen opening: 0.080 (2,03) to 0.085 (2,16).  
Paste screen thickness: 0.006 (0,15).
- H. Pad type: Solder mask defined.
- I. All pins: Material – Copper Alloy  
Finish – Tin (100%) over Nickel plate  
Solder Ball – See product data sheet.
- J. Dimension prior to reflow solder.

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Mailing Address: Texas Instruments  
Post Office Box 655303 Dallas, Texas 75265